

REV.	DATE	DCN NO.	CHANGE CONTENT	DR.	CHK.	APPD.	APPD.
2	19.Oct.2005	058469	ADDED NEW ITEMS		K.INOUE		O.HASHIGUCHI
3	24.Nov.2005	058588	ADDED NEW ITEMS		K.INOUE		O.HASHIGUCHI

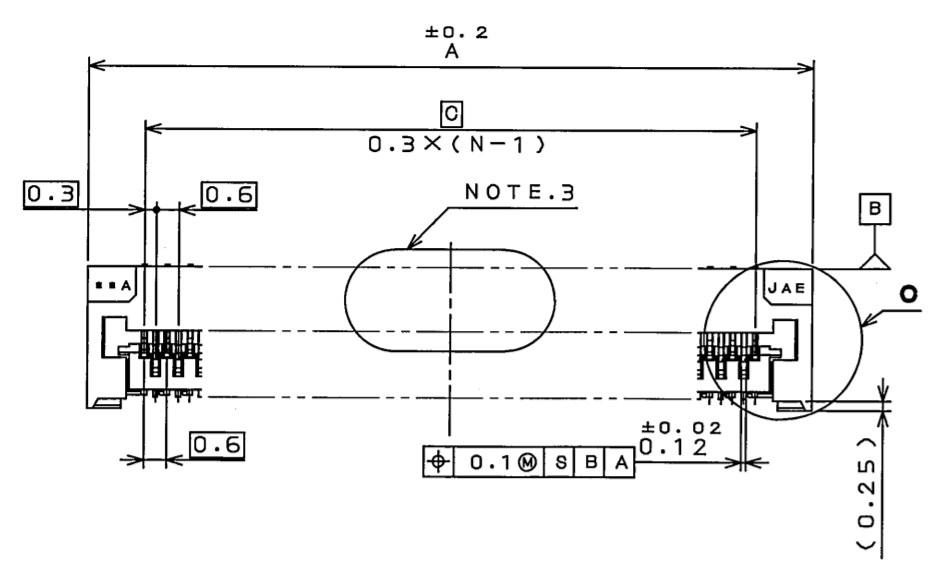
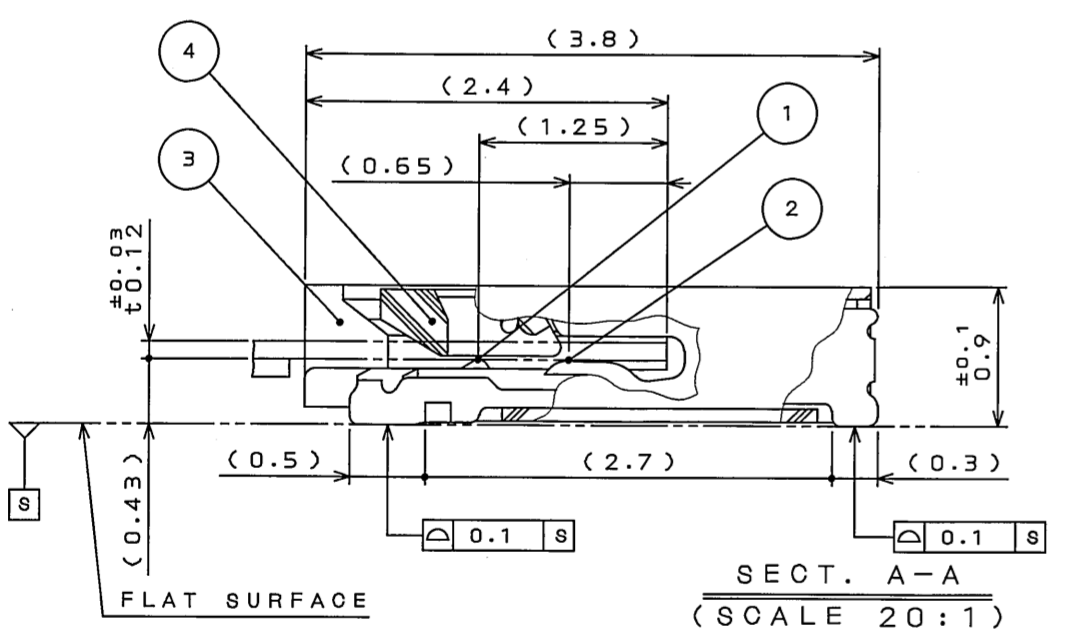
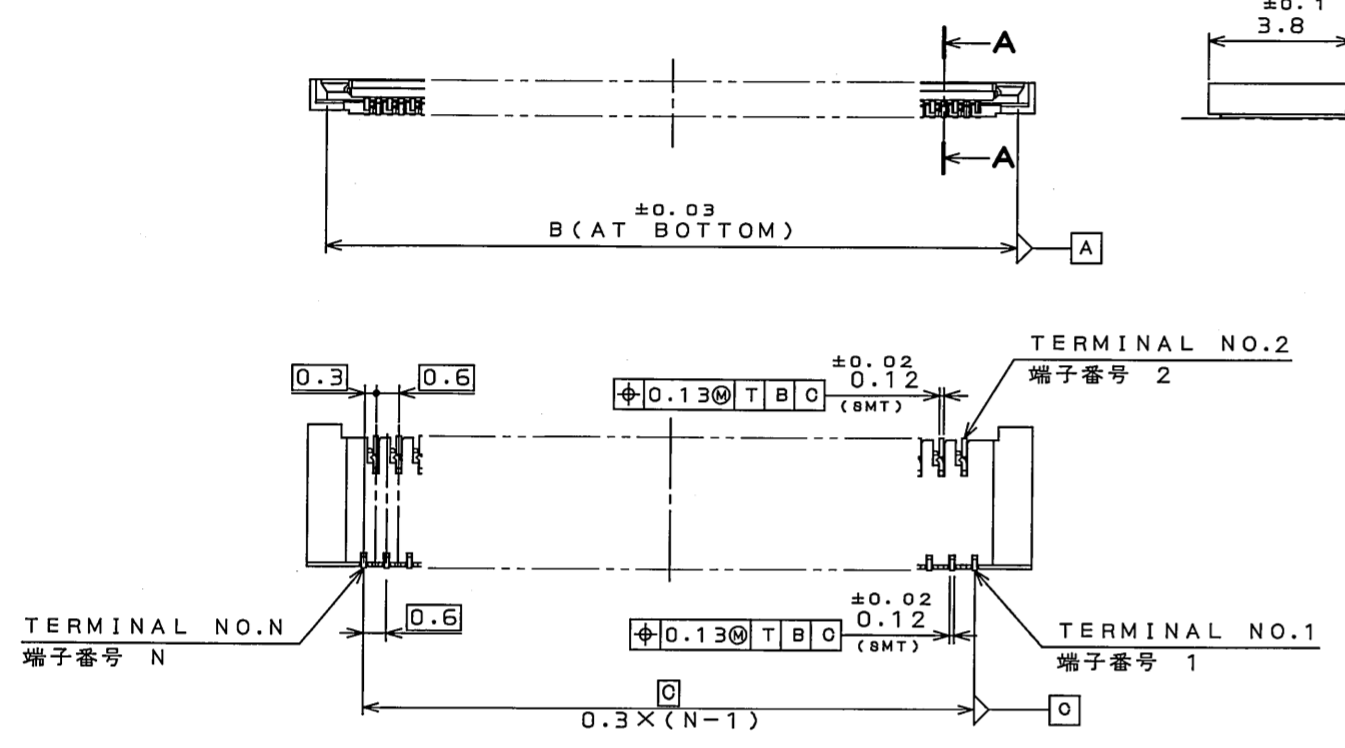
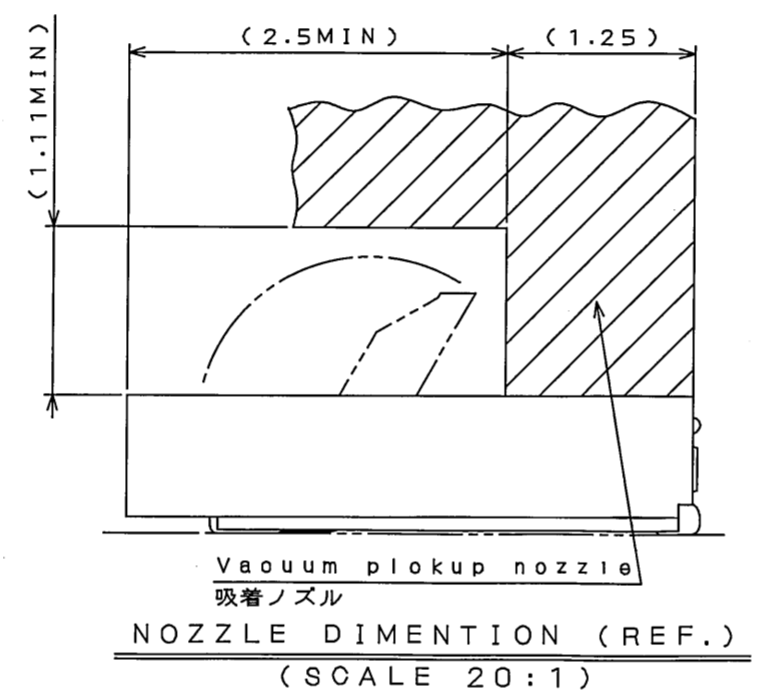
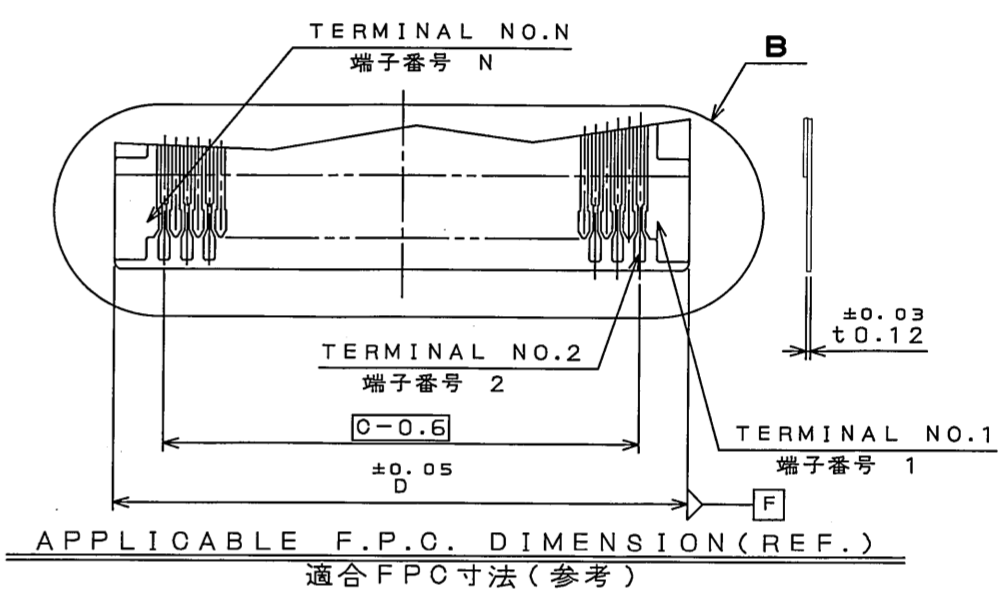
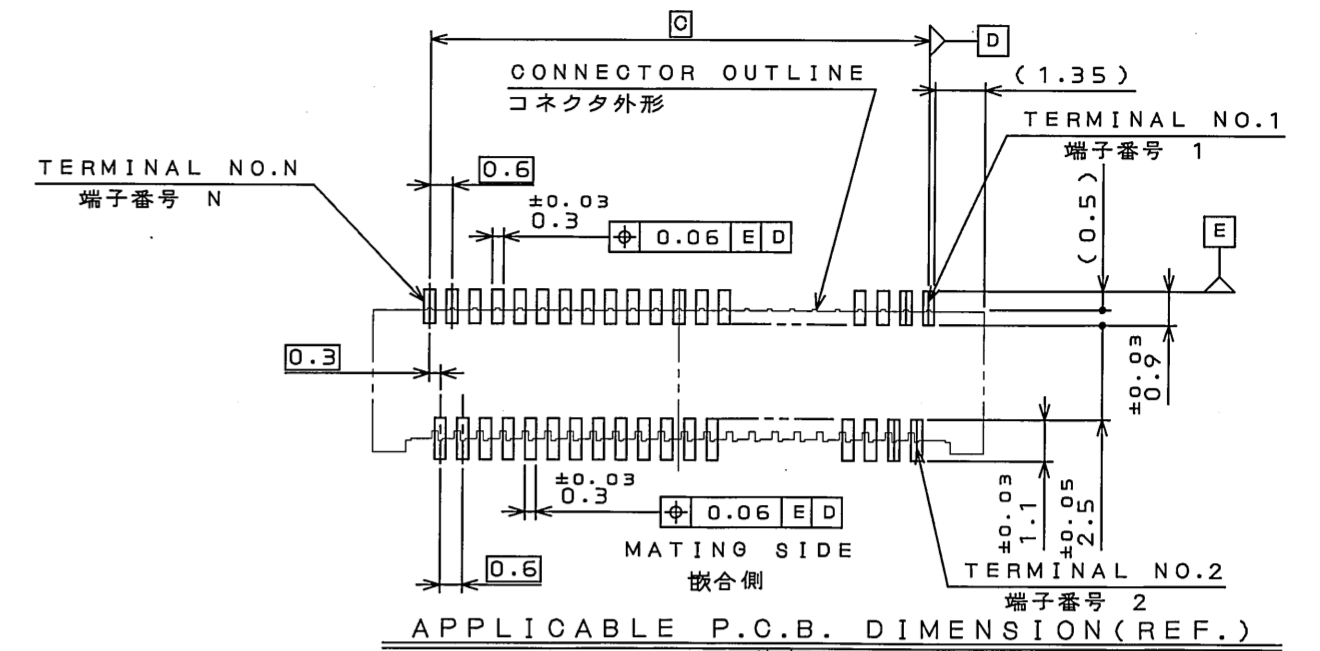


TABLE 1

PRODUCT NO.	A	B	C	D
FF028658V1	22.2	21.31	19.2	21.24
FF028558V1	19.2	18.31	16.2	18.24
FF028458V1	16.2	15.31	13.2	15.24
FF028358V1	13.2	12.31	10.2	12.24
FF028338V1	12.6	11.71	9.6	11.64
FF028318V1	12.0	11.11	9.0	11.04
FF028298V1	11.4	10.51	8.4	10.44
FF028278V1	10.8	9.91	7.8	9.84
FF028258V1	10.2	9.31	7.2	9.24
FF028178V1	7.8	6.91	4.8	6.84
FF028158V1	7.2	6.31	4.2	6.24



NOTE 1. REFER TO TABLE2 ABOUT RCOMMENDED FPC COMPOSITION.
 NOTE 2. TOERANCE OF DIMENSION D IS RECOMMENDED TO BE ± 0.05 IN ORDER TO IMPROOVE PRECISION OF PITCH POSITIONING AND CONNECTION RELIABILITY.
 NOTE 3. LOT NUMBER IS MARKED ON THE TOP CENTER PORTION OF THE CONNECTOR.

注1.推奨FPC構成はTABLE2参照のこと。
 注2.寸法Dはピッチ方向の位置決め精度を高め接触信頼性を高めるために ± 0.05 を推奨する。
 注3.ロット番号がコネクタ上面中央部に表記される。

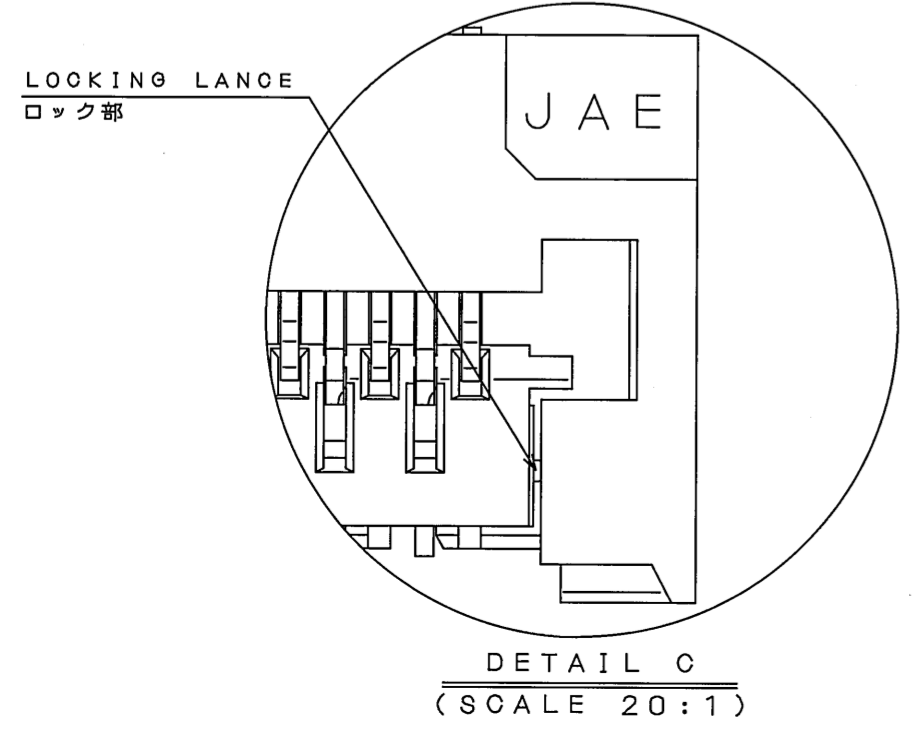
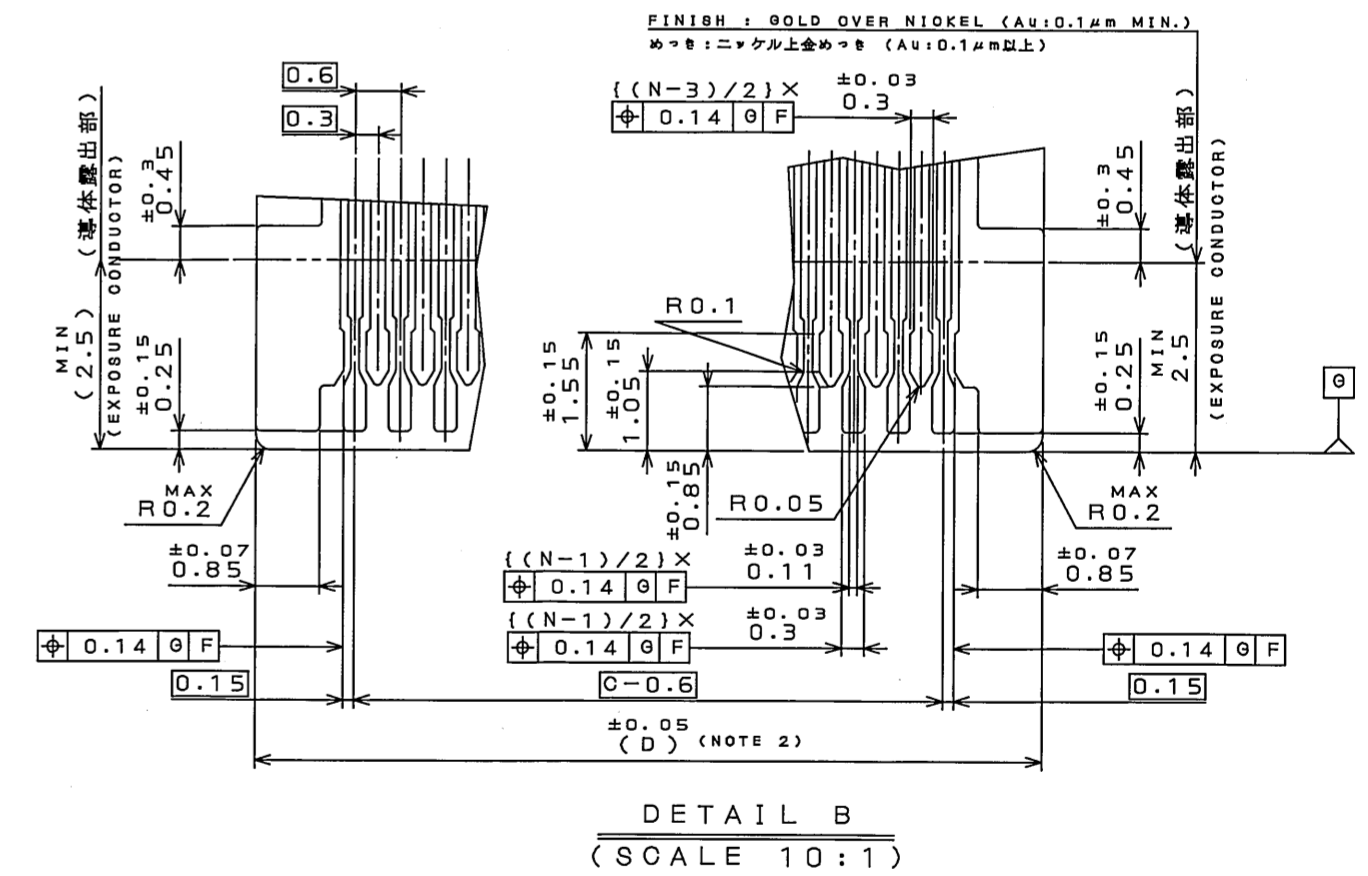


TABLE 2

COMPOSITION		RECOMMENDED
層名		推奨
GOLD PLATING	ELECTROLYSIS PLATING	0.1μm MIN
金めっき	電解めっき	
NICKEL PLATING	ELECTROLYSIS PLATING	SOFT TYPE
ニッケルめっき	電解めっき	IF AVAILABLE
COPPER	ROLLED MATERIAL	NOMINAL
銅箔	圧延銅	18μm MAX
ADHESIVE	THERMOSETTING ADHESIVE	NONE
接着剤	熱硬化性	(RECOMMENDED)
BASE FILM	POLYIMIDE	25μm
ベースフィルム	ポリイミド	
ADHESIVE	THERMOSETTING ADHESIVE	30μm MAX
接着剤	熱硬化性	
REINFORCE PLATE	POLYIMIDE	-
補強板	ポリイミド	

4	ACTUATOR	1	PPS		COLOR:BLACK/色相:黒
3	BASE INSULATOR	1	LCP		UL94V-0
2	CONTACT 2	(N-1)	COPPER ALLOY		COLOR:WHITE/色相:白
1	CONTACT 1	(N-1)	COPPER ALLOY		UL94V-0
仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE)		尺取 (SCALE)	シリーズ (SERIES)	備考
JACS-10293-*	14.Jul.2005		5:1	FF02S	日本航空電子工業株式会社
公差 (GENERAL TOLERANCE)	製造 DR.	検査 CHK.	名称 (TITLE)		
寸法 (DIMENSION)	承認 APPD.	承認 APPD.	FF02S*SV1		
. ±0.8	×° ±	××° ±	(ODD NUMBER OF CONTACTS)		
.X ±0.4			(奇数芯数)		
.XX ±0.1			質量 (MASS)		
.XXX ±			図面番号 (DRAWING NO.)		
			SJ104079		

DDF-0-213E(03.08)

SIZE A2